

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _R WM V _R	75	V
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current (Note 5)	I _{FM}	300	mA
Average Rectified Output Current (Note 5)	Io	150	mA
Repetitive Peak Forward Current	I _{FRM}	450	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0µs @ t = 1.0s	I _{FSM}	2.0 1.0	A

Thermal Characteristics

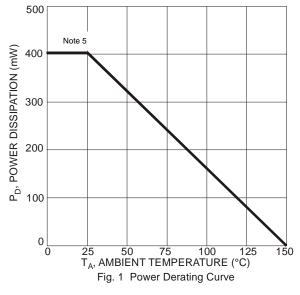
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	312	°C/W
Operating and Storage Temperature Range	T_J,T_STG	-65 to +150	°C

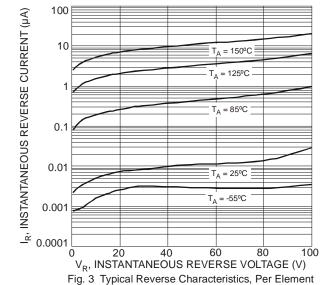
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

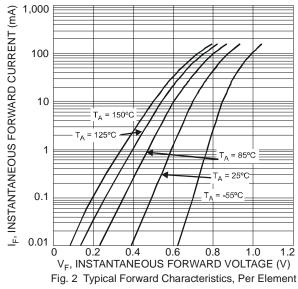
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	75		V	$I_R = 2.5\mu A$
Forward Voltage	V _F		0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 6)	I _R		2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$, $T_J = +150^{\circ}C$ $V_R = 25V$, $T_J = +150^{\circ}C$ $V_R = 20V$
Total Capacitance	Ст	_	2.0	pF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time	t _{RR}		4.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{RR} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

5. Part mounted on FR-4 board with recommended pad layout, please see http://www.diodes.com/package-outlines.html for the latest version.
6. Short duration pulse test used to minimize self-heating effect. Notes:









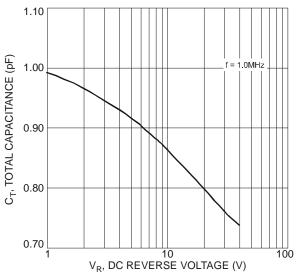


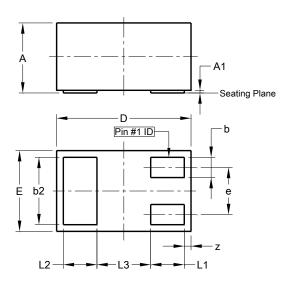
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-3

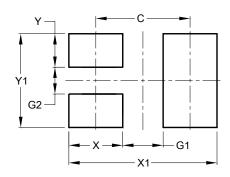


X1-DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.075	1.00	
Е	0.55	0.675	0.60	
е	ı	_	0.35	
ľ	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Υ	0.25
V1	0.70



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